

ABSTRACT

INTEGRATED CIRCUIT SYSTEM EMPLOYING BACK END OF LINE VIA TECHNIQUES

5 An integrated circuit system that includes: providing a substrate including front-end-
of-line circuitry; forming a first metallization layer over the substrate and electrically
connected to the substrate; forming a viabar or a via group over the first metallization layer;
and forming a second metallization layer over the first metallization layer and electrically
connected to the first metallization layer through either the viabar or the via group.

10 **Fig. 4**